

16085 U.S.PTO  
020504

EXPRESS MAIL NO. EV415842357US

Docket No. 85A 3501  
Date: February 5, 2004IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents  
 P.O. Box 1450  
 Alexandria, VA 22313-1450

22141 U.S.PTO  
10/1772936

C020504

Dear Sir:

Transmitted herewith for filing is the patent application for inventor(s):

YOSHIYUKI OGATA and HISASHI ARAI

For: DIE BONDING METHOD AND APPARATUS

Also enclosed are:

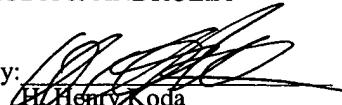
- 6 sheets of drawings
- Certified copy of Japanese Patent Application No. 2003-029183 of February 6, 2003 on which Convention priority is claimed
- Declaration and Power of Attorney
- Information Disclosure Statement by Applicant
- An assignment of the invention to KABUSHIKI KAISHA SHINKAWA

- Applicant claims Small Entity Status

CALCULATION OF FEES								
ITEM		TOTAL NO. OF CLAIMS		NO. OF CLAIMS OVER BASE	LG/SM \$ ENTITY FEE		\$ AMOUNT	\$ FEE
A	TOTAL CLAIMS FEE	4	-20	0	LG=\$18 SM=\$9	\$18	\$ 0	
B	INDEPENDENT CLAIMS FEE*	2	-3	0	LG=\$86 SM=\$43	\$86	\$ 0	
C	SUBTOTAL - ADDITIONAL CLAIMS FEE (ADD FINAL COLUMN IN LINES A + B)							\$ 0
D	MULTIPLE-DEPENDENT CLAIMS FEE							LARGE ENTITY FEE = \$290 SMALL ENTITY FEE = \$145
E	BASIC FEE							LARGE ENTITY FEE = \$770 SMALL ENTITY FEE = \$385
F	TOTAL FILING FEE (ADD TOTALS FOR LINES C, D, AND E)							\$ 385
G	ASSIGNMENT RECORDING FEE							\$ 40
	*LIST INDEPENDENT CLAIMS 1, 4							\$ 40

- The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Account No. 11-1445. A duplicate copy of this sheet is enclosed.
- A check in the amount of \$ 385 to cover the filing fee is enclosed.
- A check in the amount of \$ 40 to cover Assignment Recordation fee is enclosed.

Respectfully submitted,  
KODA & ANDROLIA

By:   
 H. Henry Koda  
 Reg. No. 27,729

2029 Century Park East  
 Suite 1430  
 Los Angeles, CA 90067-3024  
 (310) 277-1391  
 (310) 277-4118 -fax

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail No. EV415842357US addressed to:

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on February 5, 2004 by Inja Yi.

Dated: 2/5/04

By: Inja Yi

85A 3501 SHINKAWA

Applicant(s): YOSHIYUKI OGATA and HISASHI ARAI

For: DIE BONDING METHOD AND APPARATUS